



Product Change Notification

Change Notification #: 117015 - 00
Change Title: Intel® Server Accessory Kit
AUP8X25S3DPDK,
PCN 117015-00, Product Design,
Hot-Swap Back Plane Firmware Update
Date of Publication: June 19, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

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| Date Customer Must be Ready to Receive Post-Conversion Material:* | July 8, 2019 |
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*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is updating the Hot-Swap Back Plane (HSBP) firmware from version 1.19 to 1.41 of the Intel Server Hot-Swap Back Plane used in the accessory kits listed in the "Products Affected" table below. The firmware version 1.41 fixes a fault LED issue found on manufacturing.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

| Product Code | MM# | Pre Change TA | Pre Change PBA | Post Change TA | Post Change PBA |
|---------------|--------|---------------|----------------|----------------|-----------------|
| AUP8X25S3DPDK | 953392 | J32847-001 | G97166-272 | J32847-002 | G97166-273 |

PCN Revision History:

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|--------------------------|-------------------------|--------------------------|
| Date of Revision: | Revision Number: | Reason: |
| June 19, 2019 | 00 | Originally Published PCN |



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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